

Features

- Uses CRM(CQ) advanced SkyMOS2 technology
- Extremely low on-resistance $R_{DS(on)}$
- Excellent $Q_g \times R_{DS(on)}$ product(FOM)
- Qualified according to JEDEC criteria

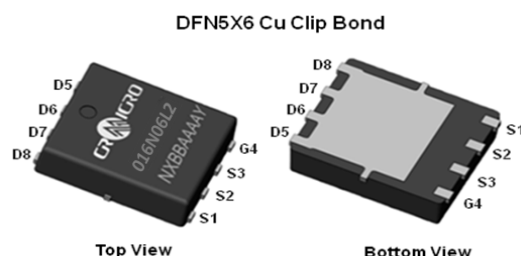
Applications

- Synchronous Rectification for AC/DC Quick Charger
- Battery management
- UPS (Uninterruptible Power Supplies)

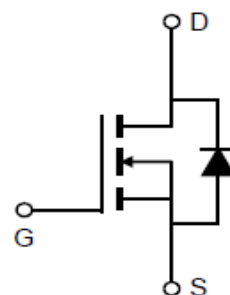
Product Summary

V_{DS}	60V
$R_{DS(on)@10V\ typ}$	1.5mΩ
I_D	215A

100% Avalanche Tested
100% DVDS Tested



CRSM016N06L2



Package Marking and Ordering Information

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
CRSM016N06L2	016N06L2	DFN5x6 Clip	Tape&Reel	N/A	N/A	4000pcs

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	60	V
Continuous drain current	I_D	- 215 136	A
$T_C = 25^\circ\text{C}$ (Silicon limit)			
$T_C = 100^\circ\text{C}$ (Silicon limit)			
Pulsed drain current ($T_C = 25^\circ\text{C}$, t_p limited by T_{jmax})	$I_{D\ pulse}$	860	A
Avalanche energy, single pulse ($L=0.3\text{mH}$, $V_{ds}=30\text{V}$)	E_{AS}	1161	mJ
Gate-Source voltage	V_{GS}	± 20	V
Power dissipation ($T_C = 25^\circ\text{C}$)	P_{tot}	139	W
Operating junction and storage temperature	T_j, T_{stg}	-55...+150	$^\circ\text{C}$
Soldering temperature, wave soldering only allowed at leads (1.6mm from case for 10s)	T_{sold}	260	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Thermal resistance, junction – case.	RthJC	-	-	0.9	°C/W	-
Thermal resistance, junction - ambient(min. footprint)	RthJA	-	-	56	°C/W	-

Electrical Characteristic (at Tj = 25 °C, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

Static Characteristic

Drain-source breakdown voltage	BV _{DSS}	60	-	-	V	V _{GS} =0V, I _D =250uA
Gate threshold voltage	V _{GS(th)}	1.2	-	2.2	V	V _{DS} =V _{GS} , I _D =250uA
Zero gate voltage drain current	I _{DSS}	-	0.02	1	μA	V _{DS} =60V, V _{GS} =0V T _j =25°C T _j =125°C
Gate-source leakage current	I _{GSS}	-	±10	±100	nA	V _{GS} =±20V, V _{DS} =0V
Drain-source on-state resistance	R _{DS(on)}	-	1.5	1.8	mΩ	V _{gs} =10V, I _d =50A
		-	2.0	2.4		V _{gs} =4.5V, I _d =50A
Transconductance	g _{fs}	-	281.9	-	S	V _{DS} =5V, I _D =125A

Dynamic Characteristic

Input Capacitance	C _{iss}	2357	4714	7071	pF	V _{GS} =0V, V _{DS} =30V, f=1MHz
Output Capacitance	C _{oss}	857	1714	2571		
Reverse Transfer Capacitance	C _{rss}	35	69	138		
Gate Total Charge	Q _G	38.3	76.6	114.9	nC	V _{ds} =30V, I _d =125A , V _{gs} =10V
Gate-Source charge	Q _{gs}	8.79	17.57	26.36		
Gate-Drain charge	Q _{gd}	5.8	11.5	23.0		
Turn-on delay time	t _{d(on)}	6.4	12.8	19.2	ns	V _{GS} =10V, V _{DD} =30V, R _{G_ext} =2.7Ω, I _D =125A
Rise time	t _r	51	102	153		
Turn-off delay time	t _{d(off)}	21.4	42.7	64.1		
Fall time	t _f	107	214	321		
Gate resistance	R _G	0.5	0.9	1.4	Ω	V _{GS} =0V, V _{DS} =0V, f=1MHz

Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	-	0.88	1.32	V	$V_{GS}=0V, I_{SD}=50A$
Body Diode Continuous Forward Current	I_S	-	-	215	A	TC = 25°C
Body Diode Pulsed Current	I_S pulse	-	-	860	A	TC = 25°C
Body Diode Reverse Recovery Time	t_{rr}	23.3	46.7	93.4	ns	$I_F=70A, dI/dt=300A/\mu s, V_{ds}=60V$
Body Diode Reverse Recovery Charge	Q_{rr}	63.3	126.6	253.3	nC	

Typical Performance Characteristics

Fig 1: Output Characteristics

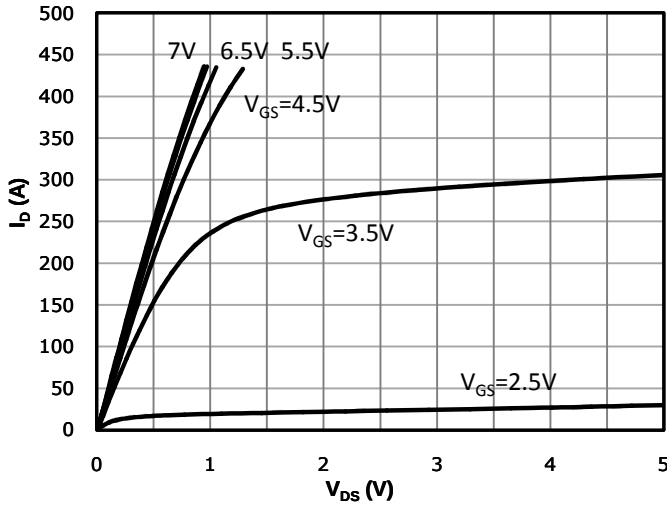


Fig 2: Transfer Characteristics

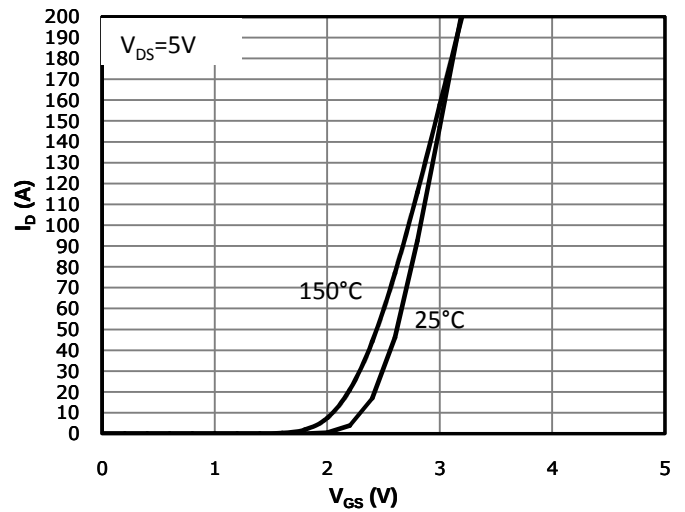


Fig 3: $R_{DS(on)}$ vs Drain Current and Gate Voltage

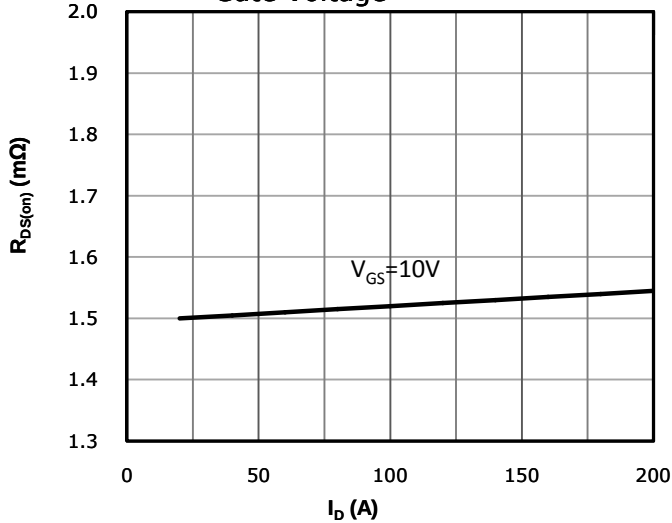


Fig 4: $R_{DS(on)}$ vs Gate Voltage

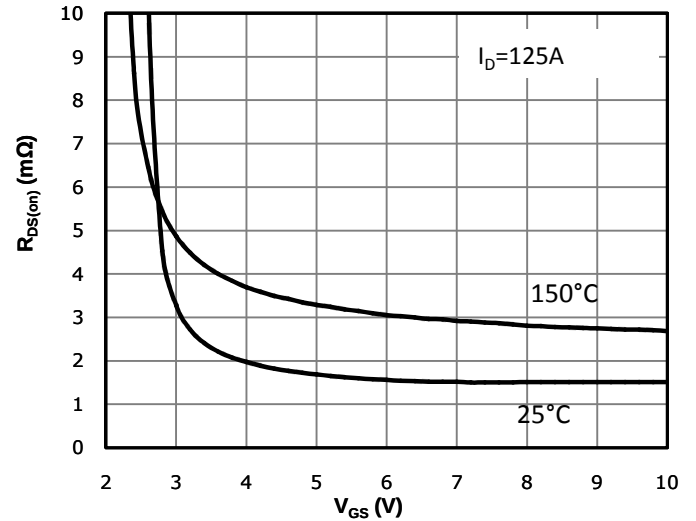


Fig 5: $R_{DS(on)}$ vs. Temperature

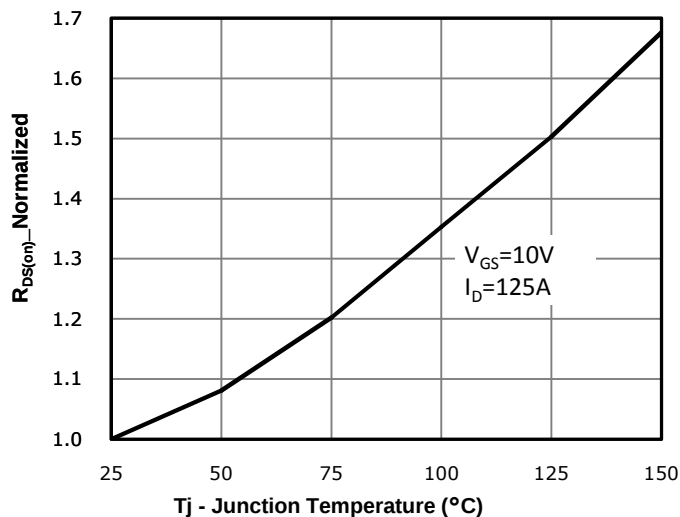


Fig 6: Capacitance Characteristics

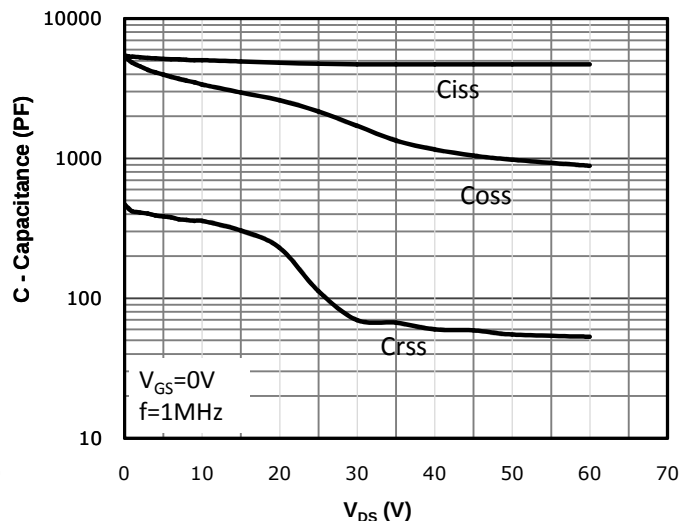


Fig 7: Gate Charge Characteristics

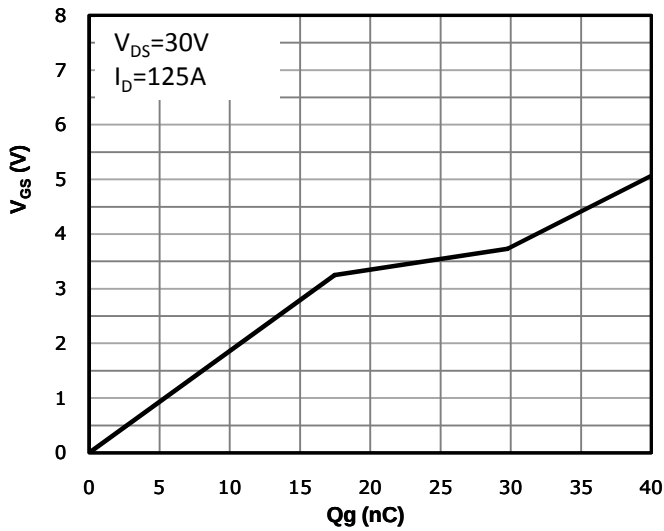


Fig 8: Body-diode Forward Characteristics

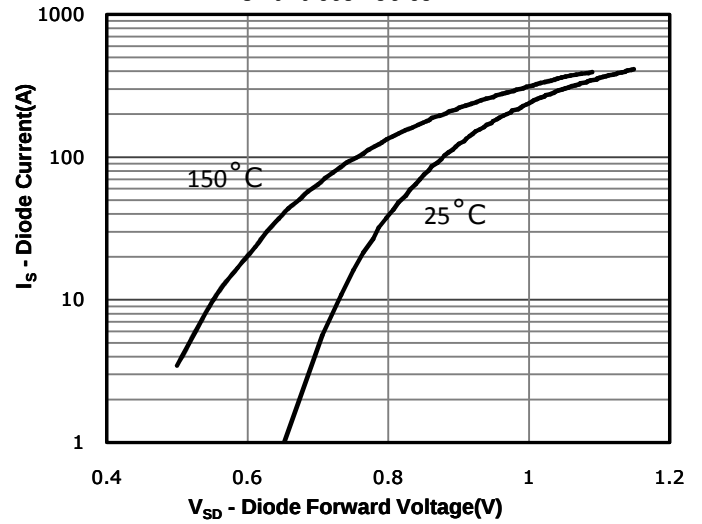


Fig 9: Power Dissipation

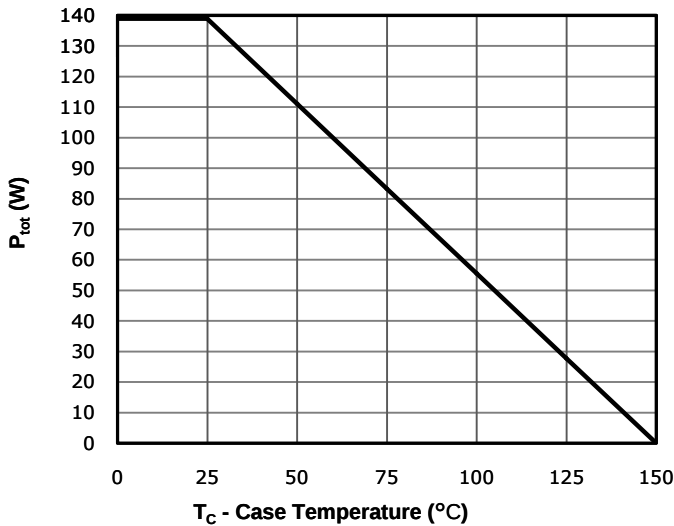


Fig 10: Drain Current Derating

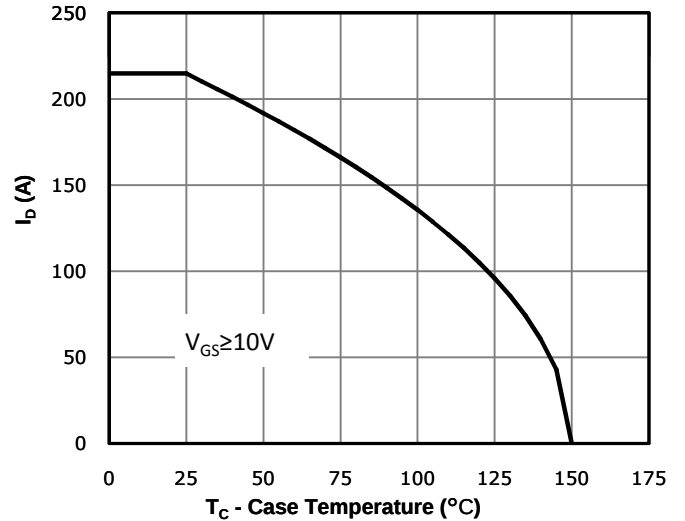


Fig 11: Safe Operating Area

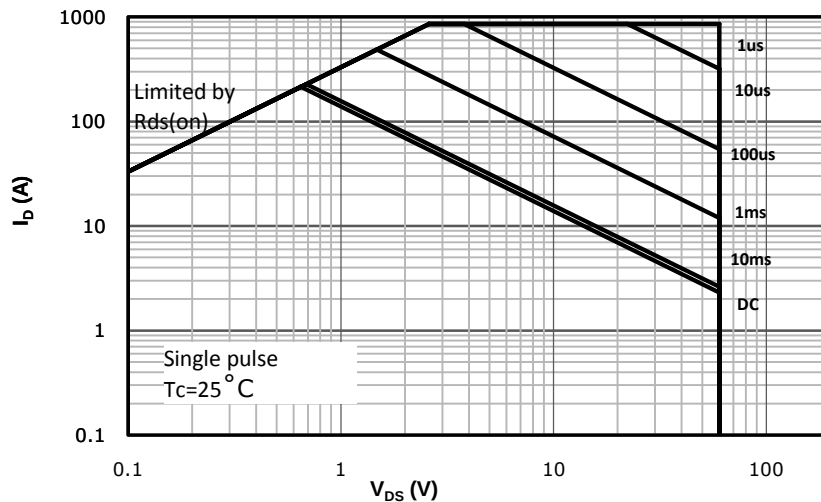
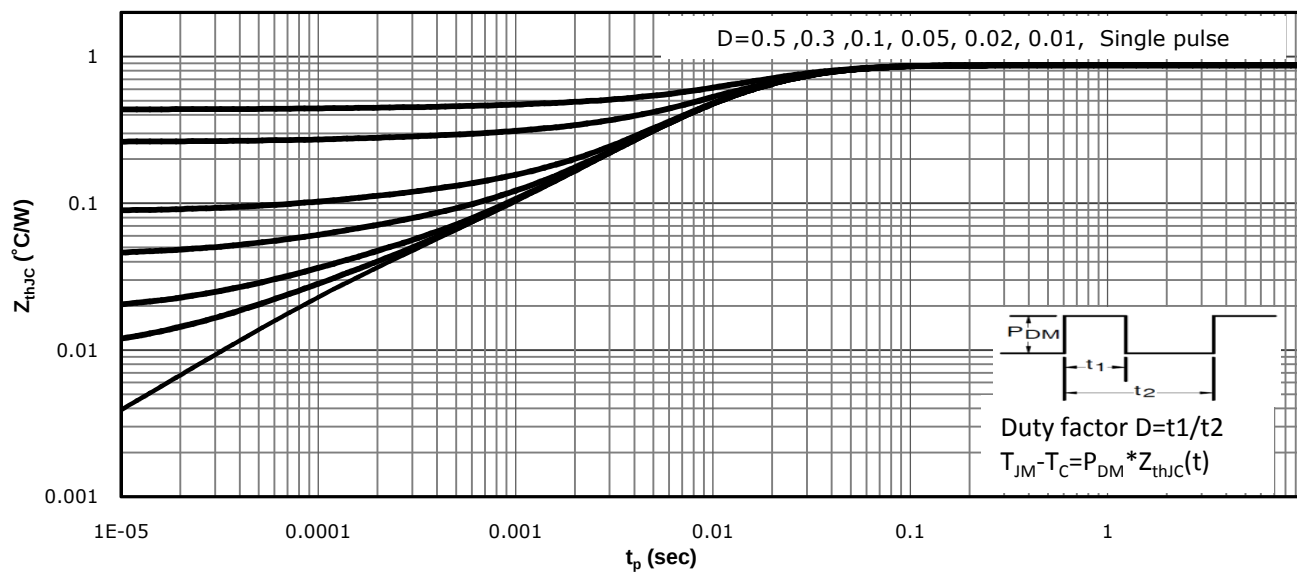
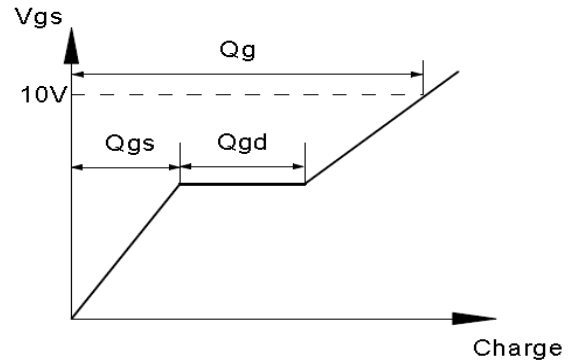
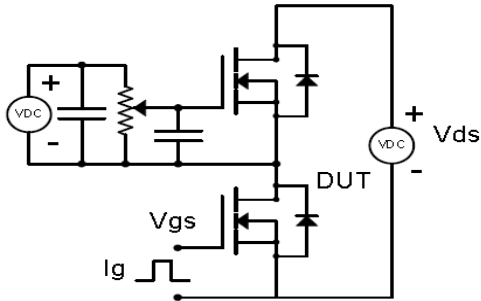


Fig 12: Max. Transient Thermal Impedance

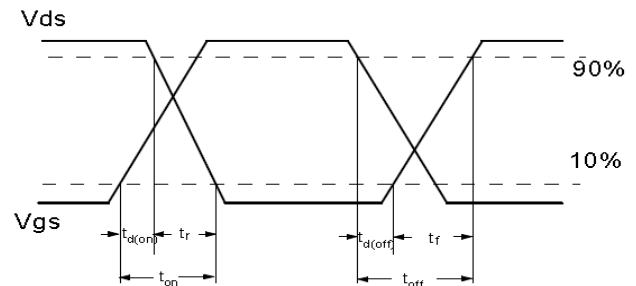
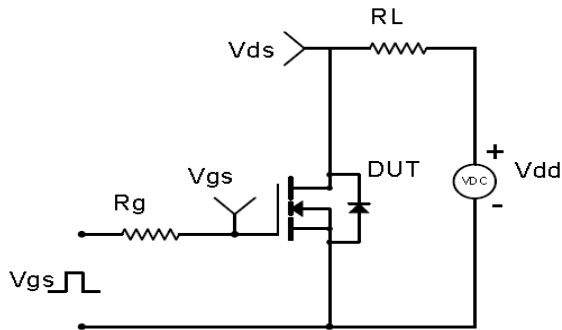


Test Circuit & Waveform

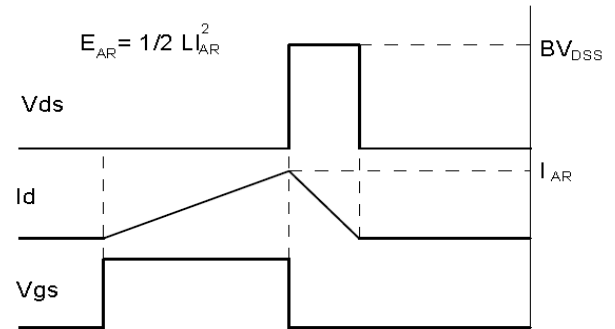
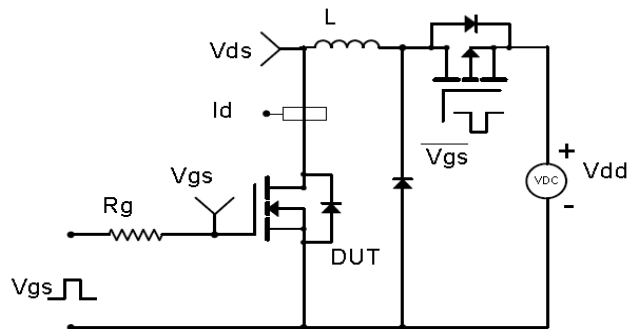
Gate Charge Test Circuit & Waveform



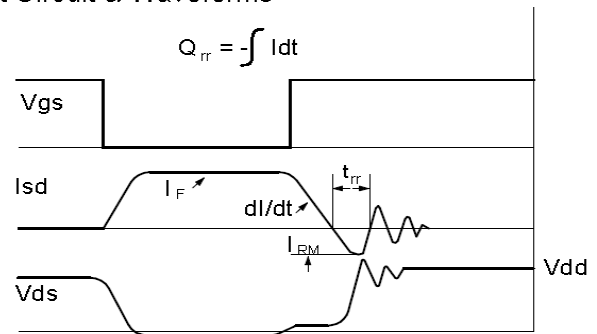
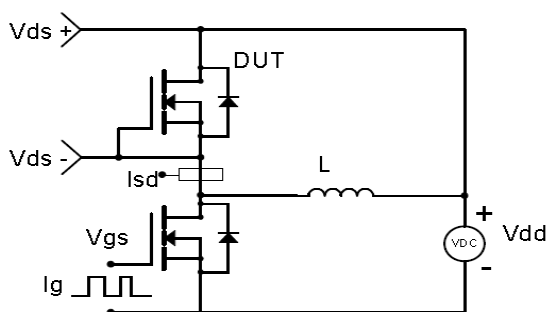
Resistive Switching Test Circuit & Waveforms



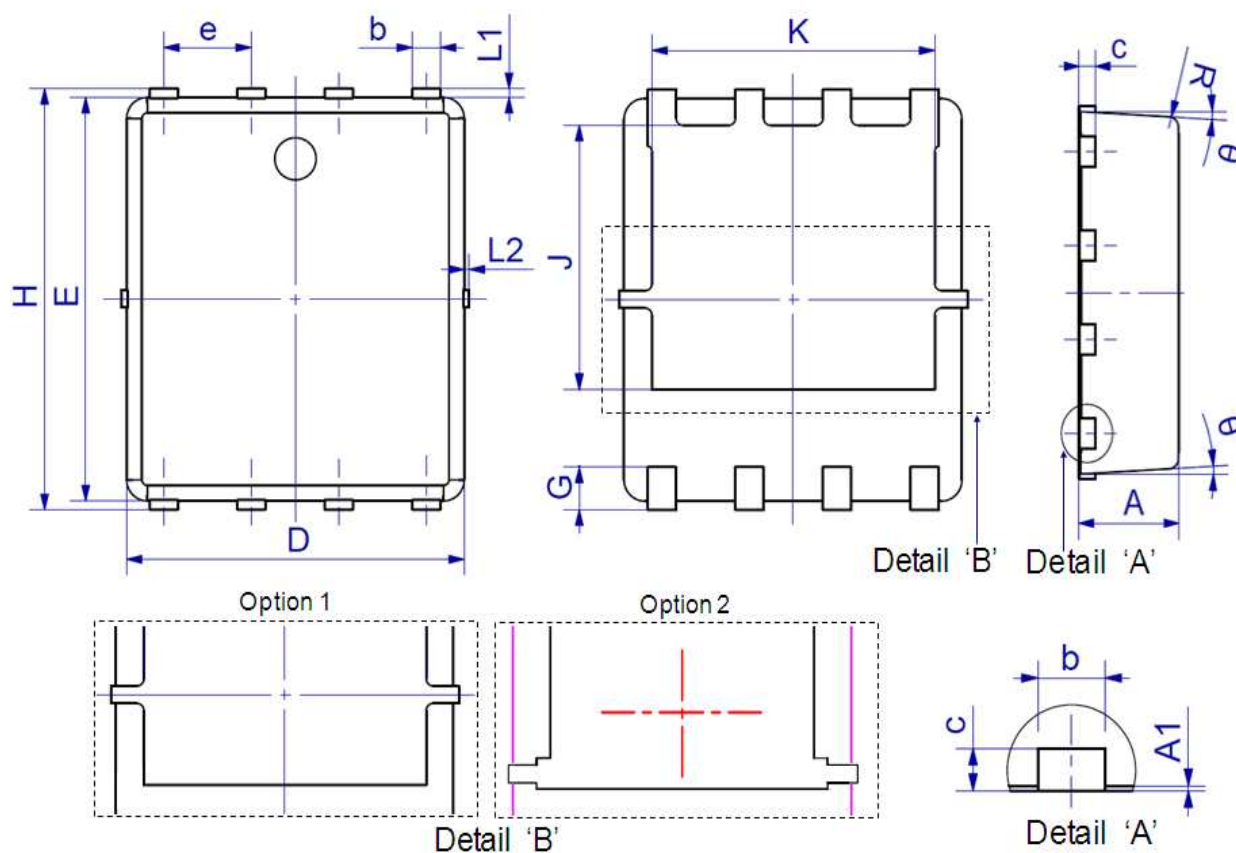
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Outline: DFN5X6 Cu Clip



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.80	1.20	0.031	0.047
A1	0.00	0.05	0.000	0.002
b	0.30	0.51	0.012	0.020
c	0.15	0.35	0.006	0.014
D	4.80	5.40	0.189	0.213
e	1.27 BSC		0.050 BSC	
E	5.66	6.06	0.223	0.239
G	0.30	0.71	0.012	0.028
H	5.90	6.35	0.232	0.250
J	3.32	3.92	0.131	0.154
K	3.61	4.25	0.142	0.167
L1	0.05	0.25	0.002	0.010
L2	0.00	0.15	0.000	0.006
R	0.25 REF		0.010 REF	
θ	0°	12°	0°	12°

Marking



NOTE:

NXBBAAAAY

N	—Wire Bond code
X	—Assembly location code
BB	—Fab code
AAAA	—Lot code
Y	—Bin code

Revision History

Revision	Date	Major changes
1.0	2020-4-9	Release of Formal Version.
1.1	2020-9-16	Add min and max of dynamic characteristic.
1.2	2020-12-14	Revise Ron test condition and spec.

Disclaimer

Unless otherwise specified in the datasheet, the product is designed and qualified as a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability, such as automotive, aviation/aerospace and life-support devices or systems.

Any and all semiconductor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.

CRM(CQ) reserves the right to improve product design, function and reliability without notice.